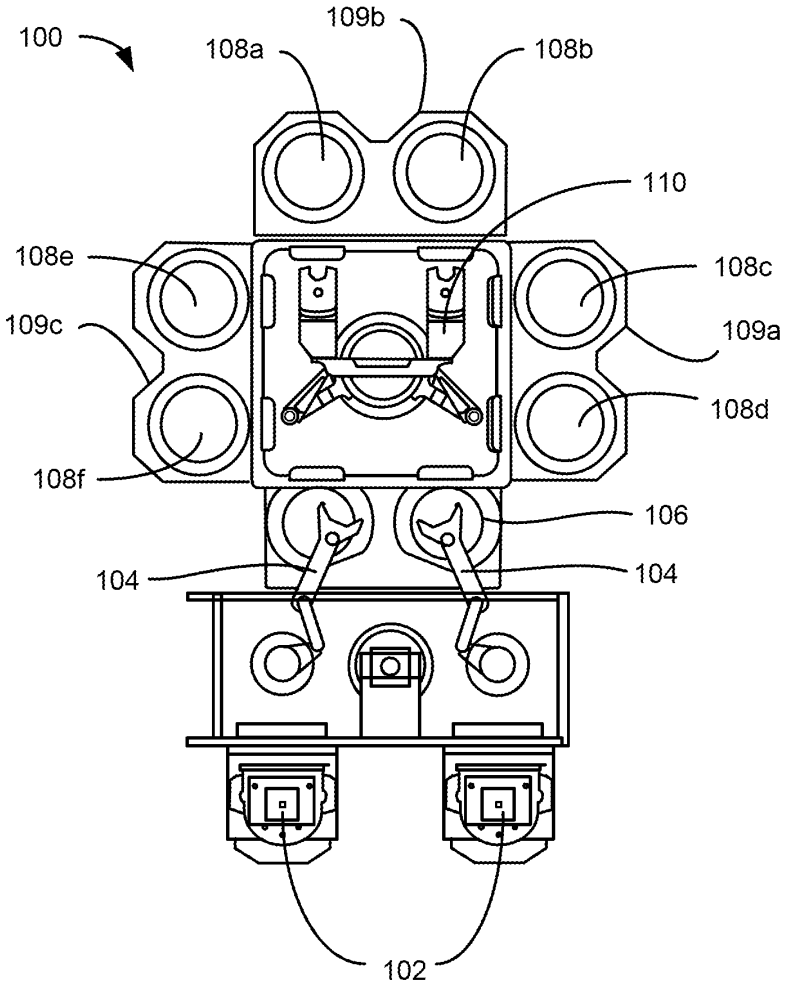
100
109b
108a
108b
110
108e
108c
109c
109a
108d
108f
106
104
104
102

FIG. 1

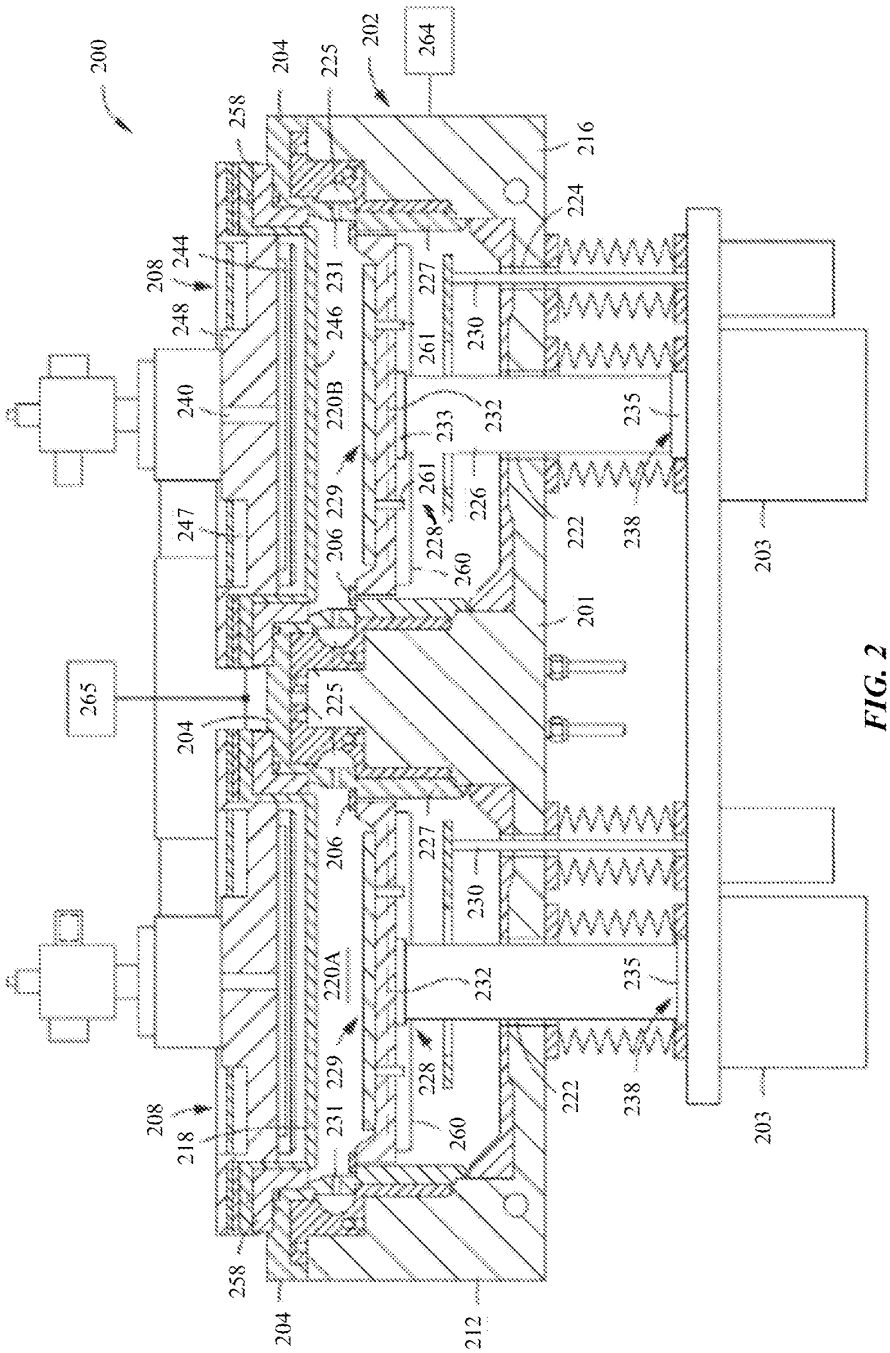
200
202
264
204
225
258
216
224
208
244
248
231
227
246
261
230
240
220B
232
233
235
229
261
226
222
238
247
206
228
260
203
201
265
204
225
206
227
230
220A
232
235
229
228
222
238
208
218
231
260
203
258
204
212

FIG. 2

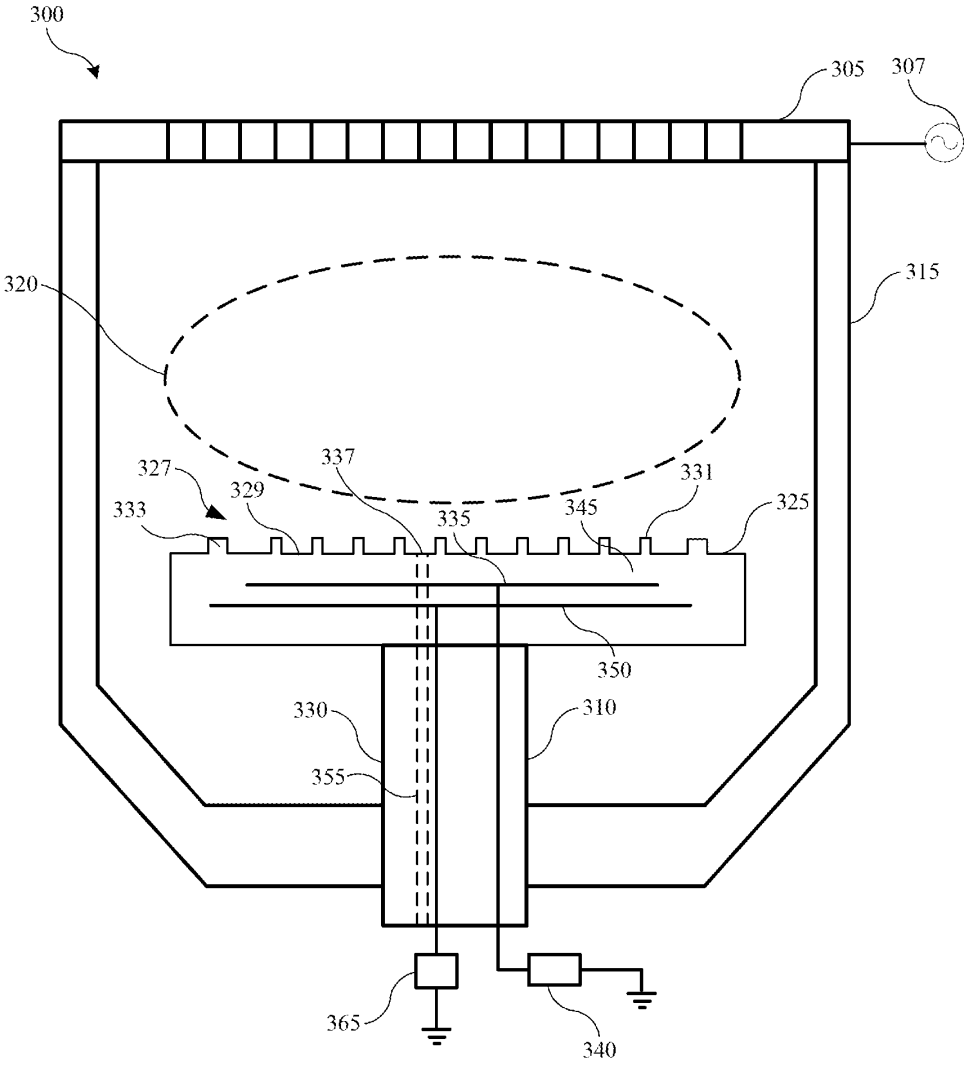
300
305
307
315
320
327
329
337
331
333
335
345
325
350
330
310
355
365
340

FIG. 3

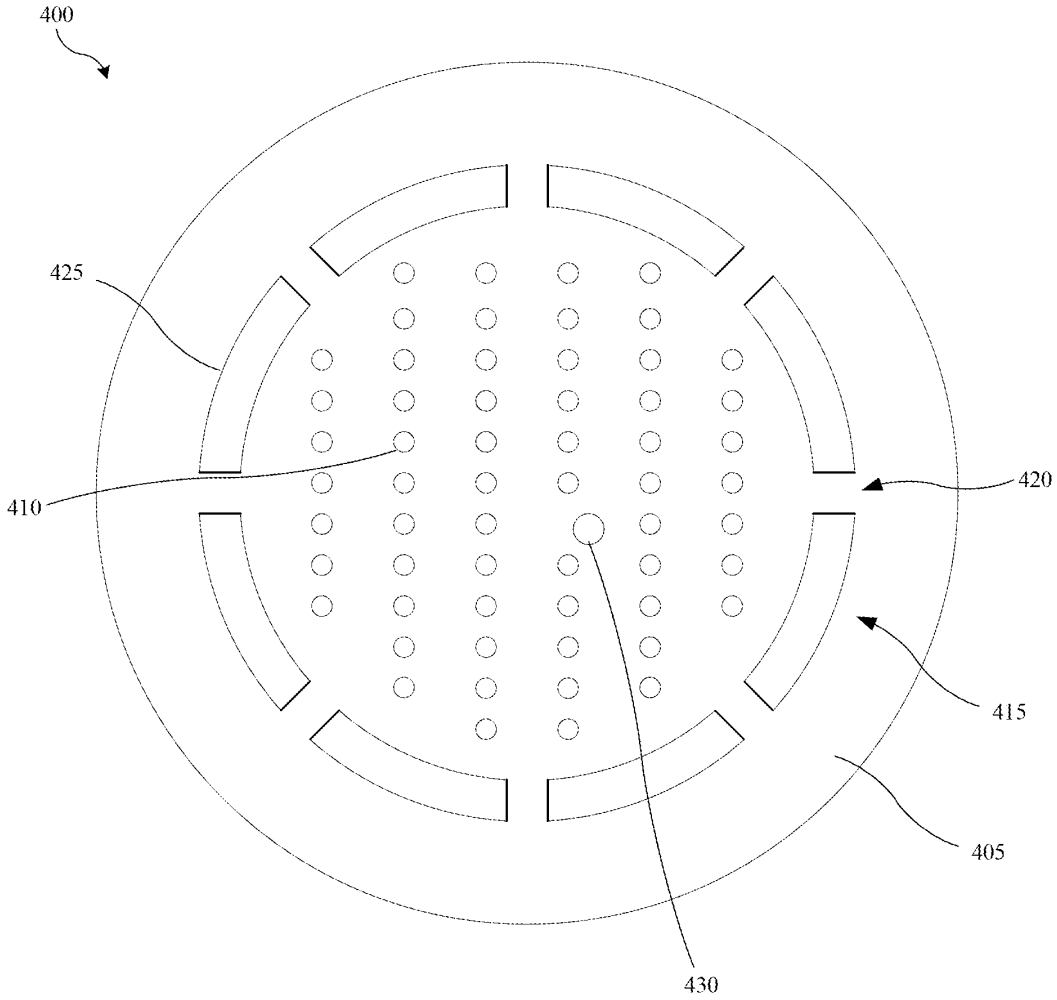

FIG. 4

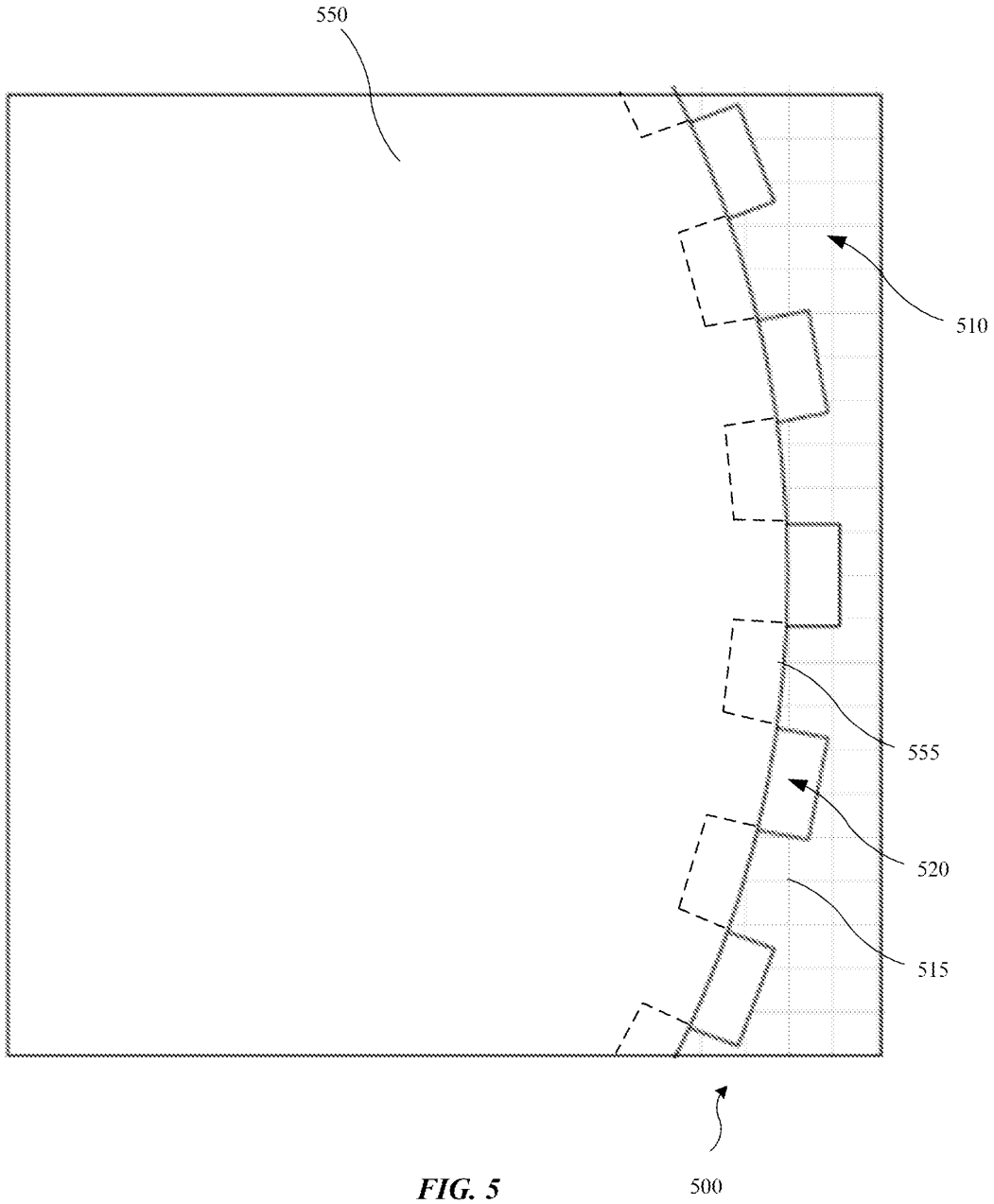

FIG. 5

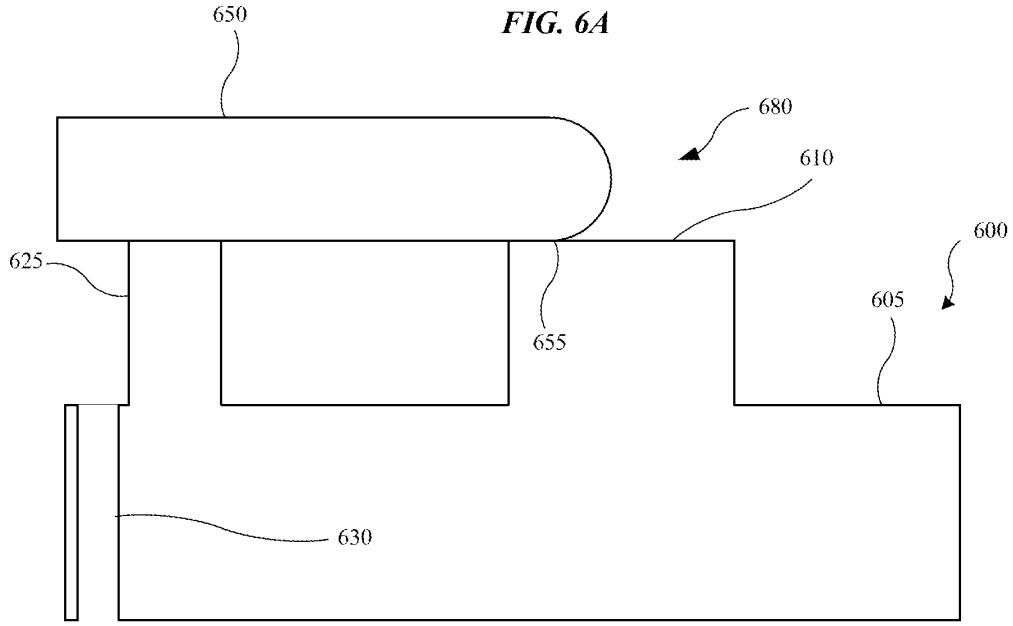
650
680
610
600
625
655
605
630

FIG. 6A

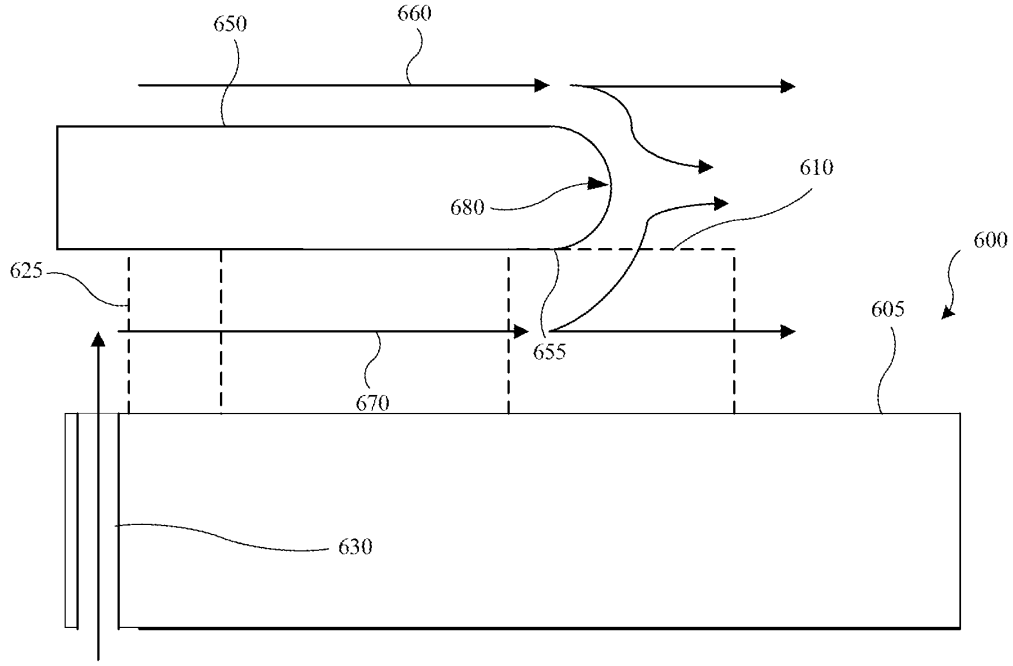
650
660
680
610
600
625
655
605
670
630

FIG. 6B

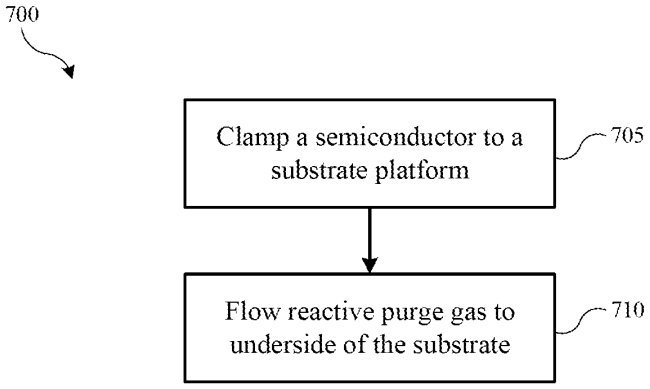
700
Clamp a semiconductor to a substrate platform
705
Flow reactive purge gas to underside of the substrate
710

FIG. 7